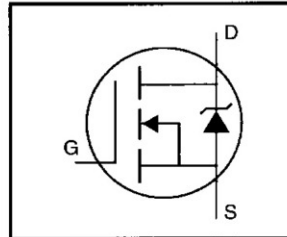


IRFP150PbF

HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- 175°C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

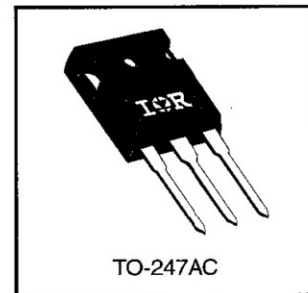


$V_{DSS} = 100V$
 $R_{DS(on)} = 0.055\Omega$
 $I_D = 41A$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-247 package is preferred for commercial–industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting hole. It also provides greater creepage distance between pins to meet the requirements of most safety specifications.



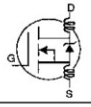
Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10 V$	41	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10 V$	29	
I_{DM}	Pulsed Drain Current ①	160	
$P_D @ T_C = 25^\circ C$	Power Dissipation	230	W
	Linear Derating Factor	1.5	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②	830	mJ
I_{AR}	Avalanche Current ①	41	A
E_{AR}	Repetitive Avalanche Energy ①	19	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.5	V/ns
T_J	Operating Junction and Storage Temperature Range	-55 to +175	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1 N•m)	

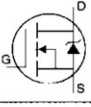
Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	0.65	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	40	

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS}=0V, I_D=250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.14	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D=1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.055	Ω	$V_{GS}=10V, I_D=25A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
g_{fs}	Forward Transconductance	13	—	—	S	$V_{DS}=25V, I_D=25A$ ④
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{DS}=100V, V_{GS}=0V$
		—	—	250		$V_{DS}=80V, V_{GS}=0V, T_J=150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS}=20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS}=-20V$
Q_g	Total Gate Charge	—	—	140	nC	$I_D=41A$
Q_{gs}	Gate-to-Source Charge	—	—	29		$V_{DS}=80V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	68		$V_{GS}=10V$ See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	16	—		$V_{DD}=50V$
t_r	Rise Time	—	120	—	ns	$I_D=41A$
$t_{d(off)}$	Turn-Off Delay Time	—	60	—		$R_G=6.2\Omega$
t_f	Fall Time	—	81	—		$R_D=1.2\Omega$ See Figure 10 ④
L_D	Internal Drain Inductance	—	5.0	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact
L_S	Internal Source Inductance	—	13	—		
C_{iss}	Input Capacitance	—	2800	—	pF	$V_{GS}=0V$
C_{oss}	Output Capacitance	—	1100	—		$V_{DS}=25V$
C_{rss}	Reverse Transfer Capacitance	—	280	—		$f=1.0\text{MHz}$ See Figure 5

Source-Drain Ratings and Characteristics

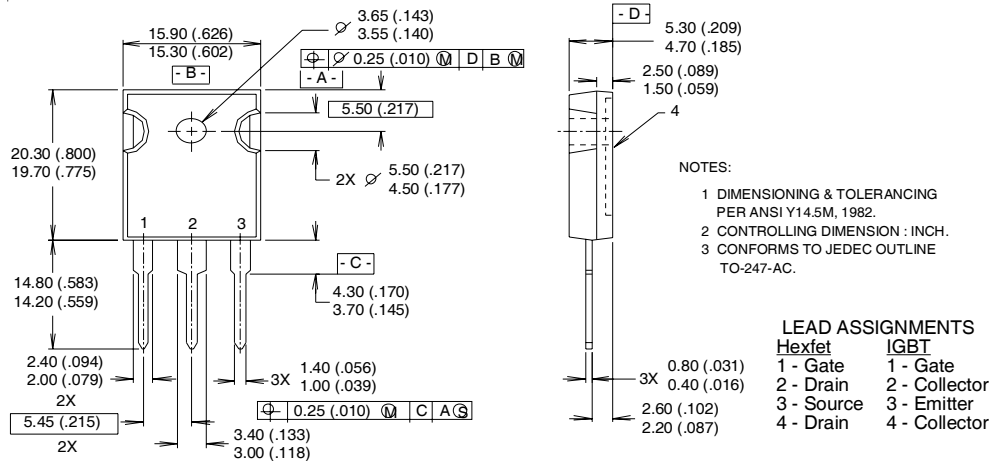
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	41	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	160		
V_{SD}	Diode Forward Voltage	—	—	2.5	V	$T_J=25^\circ\text{C}, I_S=41A, V_{GS}=0V$ ④
t_{rr}	Reverse Recovery Time	—	220	330	ns	$T_J=25^\circ\text{C}, I_F=41A$
Q_{rr}	Reverse Recovery Charge	—	1.9	2.9	μC	$di/dt=100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)
- ② $V_{DD}=25V$, starting $T_J=25^\circ\text{C}$, $L=740\mu H$, $R_G=25\Omega$, $I_{AS}=41A$ (See Figure 12)
- ③ $I_{SD}\leq 41A$, $di/dt\leq 300A/\mu s$, $V_{DD}\leq V_{(BR)DSS}$, $T_J\leq 175^\circ\text{C}$
- ④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30
 WITH ASSEMBLY
 LOT CODE 5667
 ASSEMBLED ON WW 35, 2000
 IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position indicates "Lead-Free"

